

General Description

The HSP3105 is the high cell density trenched P-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

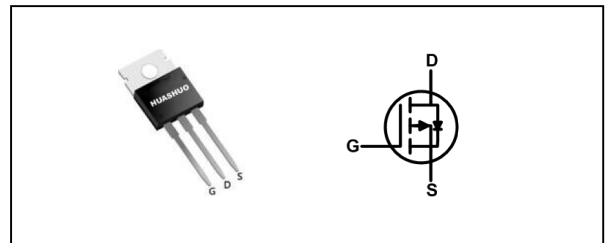
The HSP3105 meet the RoHS and Green Product requirement 100% EAS guaranteed with full function reliability approved.

- 100% EAS Guaranteed
- Green Device Available
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

Product Summary

| | | |
|------------------|-----|----|
| V_{DS} | -30 | V |
| $R_{DS(ON),max}$ | 14 | mΩ |
| I_D | -60 | A |

TO-220 Pin Configuration



Absolute Maximum Ratings

| Symbol | Parameter | Rating | Units |
|-----------------------|---|------------|-------|
| V_{DS} | Drain-Source Voltage | -30 | V |
| V_{GS} | Gate-Source Voltage | ±20 | V |
| $I_D@T_A=25^{\circ}C$ | Continuous Drain Current, $V_{GS} @ -10V^1$ | -60 | A |
| $I_D@T_A=70^{\circ}C$ | Continuous Drain Current, $V_{GS} @ -10V^1$ | -38 | A |
| I_{DM} | Pulsed Drain Current ² | -150 | A |
| EAS | Single Pulse Avalanche Energy ³ | 125 | mJ |
| I_{AS} | Avalanche Current | -50 | A |
| $P_D@T_A=25^{\circ}C$ | Total Power Dissipation ⁴ | 74 | W |
| T_{STG} | Storage Temperature Range | -55 to 150 | °C |
| T_J | Operating Junction Temperature Range | -55 to 150 | °C |

Thermal Data

| Symbol | Parameter | Typ. | Max. | Unit |
|-----------------|---|------|------|------|
| $R_{\theta JA}$ | Thermal Resistance Junction-Ambient ¹ | --- | 62 | °C/W |
| | Thermal Resistance Junction-Ambient ¹ ($t \leq 10s$) | --- | 1.68 | °C/W |
| $R_{\theta JC}$ | Thermal Resistance Junction-Case ¹ | --- | 24 | °C/W |



Electrical Characteristics ($T_J=25\text{ }^\circ\text{C}$, unless otherwise noted)

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|--------------|--|---|------|------|-----------|-----------|
| BV_{DSS} | Drain-Source Breakdown Voltage | $V_{GS}=0V, I_D=-250\mu A$ | -30 | --- | --- | V |
| $R_{DS(ON)}$ | Static Drain-Source On-Resistance ² | $V_{GS}=-10V, I_D=-30A$ | --- | 10 | 14 | $m\Omega$ |
| | | $V_{GS}=-4.5V, I_D=-15A$ | --- | 16 | 22 | |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{GS}=V_{DS}, I_D=-250\mu A$ | -1.0 | --- | -2.5 | V |
| I_{DSS} | Drain-Source Leakage Current | $V_{DS}=-24V, V_{GS}=0V, T_J=25^\circ C$ | --- | --- | -1 | μA |
| | | $V_{DS}=-24V, V_{GS}=0V, T_J=55^\circ C$ | --- | --- | -5 | |
| I_{GSS} | Gate-Source Leakage Current | $V_{GS}=\pm 20V, V_{DS}=0V$ | --- | --- | ± 100 | nA |
| g_{fs} | Forward Transconductance | $V_{DS}=-5V, I_D=-10A$ | --- | 30 | --- | S |
| R_g | Gate Resistance | $V_{DS}=0V, V_{GS}=0V, f=1MHz$ | --- | 9 | --- | Ω |
| Q_g | Total Gate Charge (-4.5V) | $V_{DS}=-15V, V_{GS}=-4.5V, I_D=-15A$ | --- | 22 | --- | nC |
| Q_{gs} | Gate-Source Charge | | --- | 8.7 | --- | |
| Q_{gd} | Gate-Drain Charge | | --- | 7.2 | --- | |
| $T_{d(on)}$ | Turn-On Delay Time | $V_{DD}=-15V, V_{GS}=-10V, R_G=3.3\Omega, I_D=-15A$ | --- | 8 | --- | ns |
| T_r | Rise Time | | --- | 73.7 | --- | |
| $T_{d(off)}$ | Turn-Off Delay Time | | --- | 61.8 | --- | |
| T_f | Fall Time | | --- | 24.4 | --- | |
| C_{iss} | Input Capacitance | $V_{DS}=-15V, V_{GS}=0V, f=1MHz$ | --- | 2215 | --- | pF |
| C_{oss} | Output Capacitance | | --- | 310 | --- | |
| C_{rss} | Reverse Transfer Capacitance | | --- | 237 | --- | |

Diode Characteristics

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|----------|--|--------------------------------------|------|------|------|------|
| I_S | Continuous Source Current ^{1,5} | $V_G=V_D=0V$, Force Current | --- | --- | -60 | A |
| V_{SD} | Diode Forward Voltage ² | $V_{GS}=0V, I_S=-1A, T_J=25^\circ C$ | --- | --- | -1 | V |

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $V_{DD}=-25V, V_{GS}=-10V, L=0.1mH, I_{AS}=-50A$
- 4.The power dissipation is limited by 150 $^\circ C$ junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

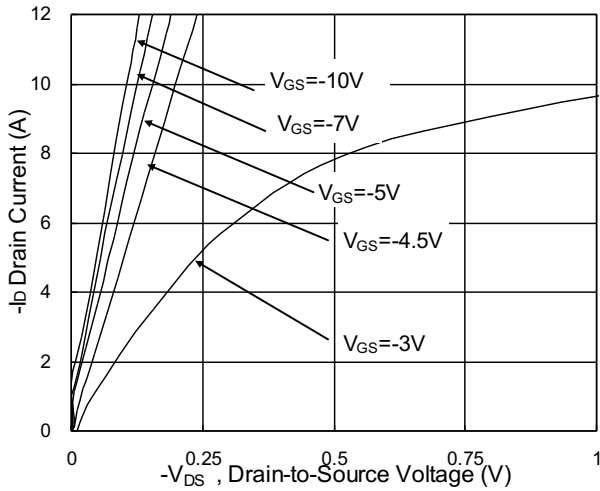


Fig.1 Typical Output Characteristics

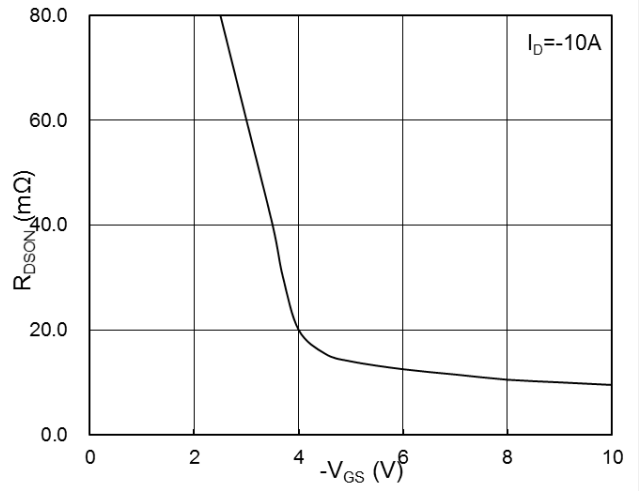


Fig.2 On-Resistance vs. G-S Voltage

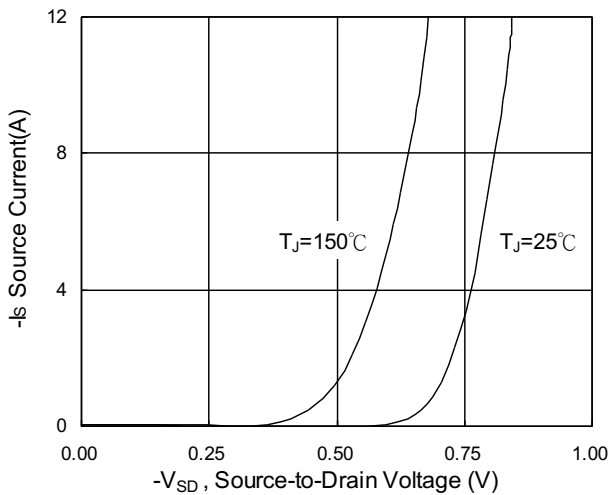


Fig.3 Source Drain Forward Characteristics

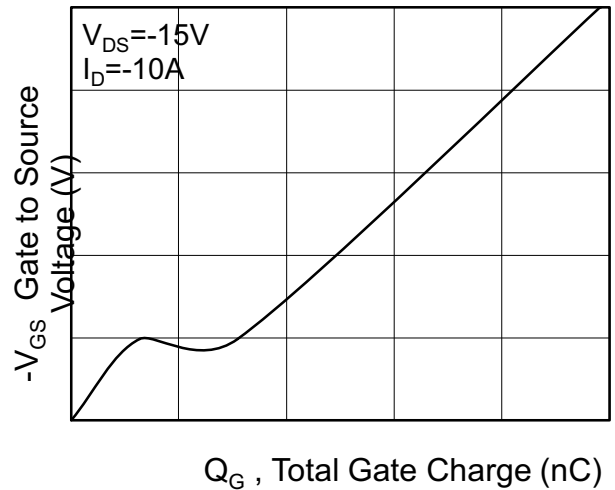


Fig.4 Gate-charge Characteristics

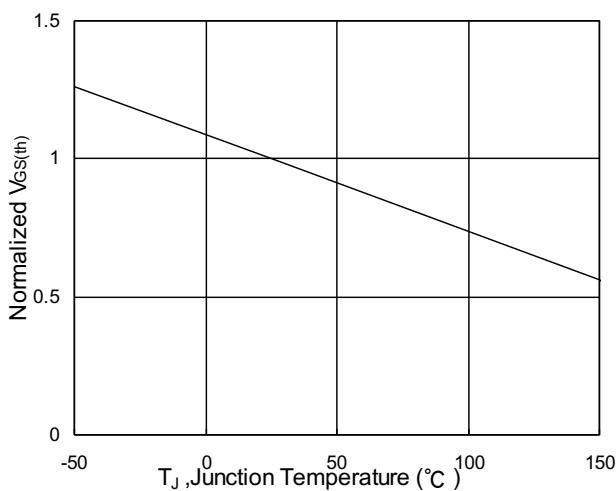


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

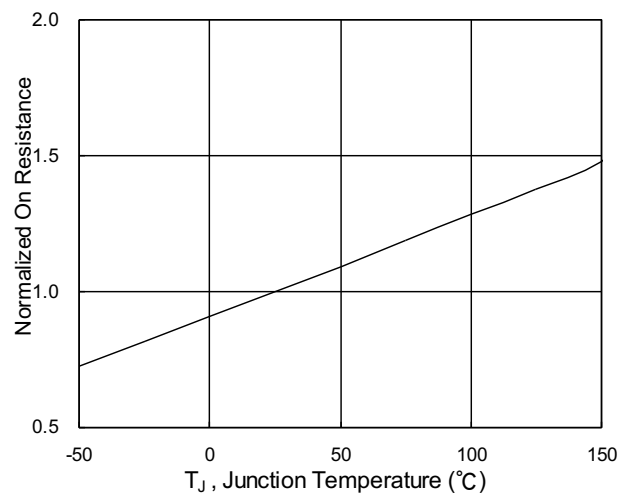


Fig.6 Normalized $R_{DS(on)}$ vs. T_J

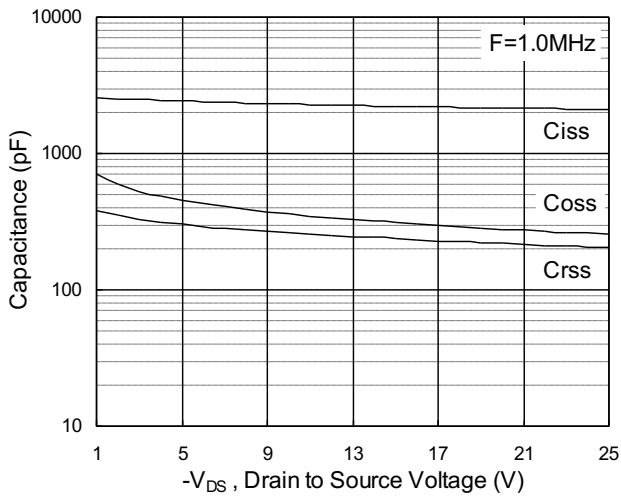


Fig.7 Capacitance

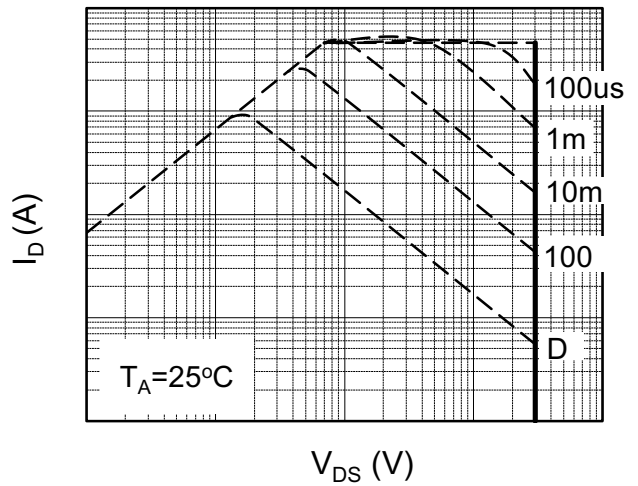


Fig.8 Safe Operating Area

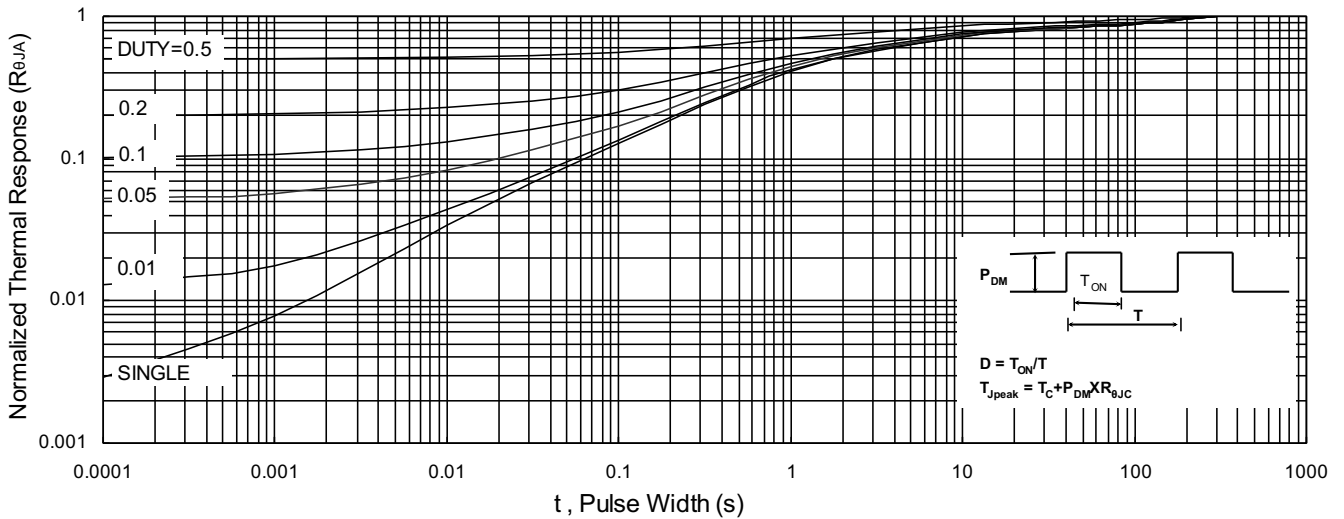


Fig.9 Normalized Maximum Transient Thermal Impedance

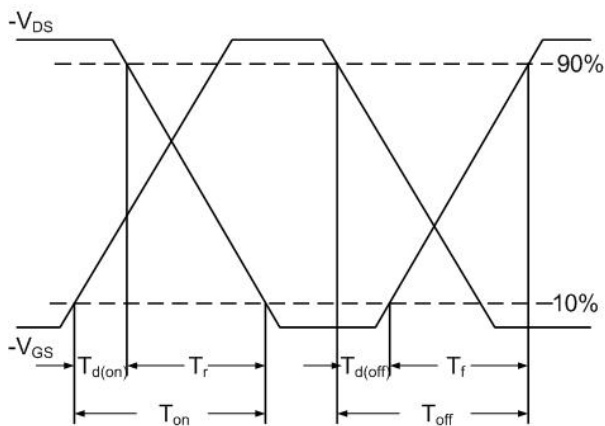


Fig.10 Switching Time Waveform

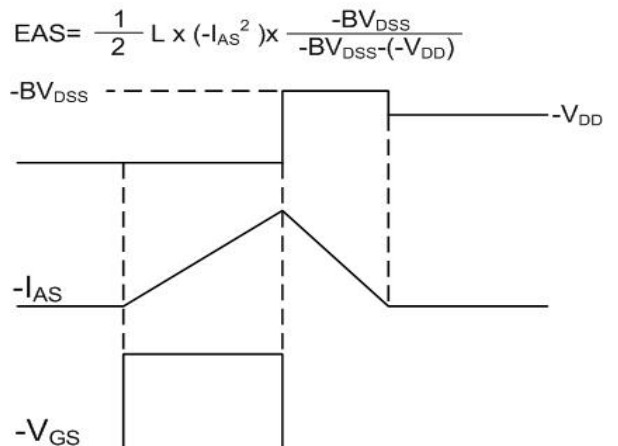


Fig.11 Unclamped Inductive Waveform

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